



(1.00 mm) .0394"

MLE-150-01-G-DV

MLE-120-01-G-DV

CLM-111-02-L-D

CLM-126-02-F-D

CLM, MLE SERIES

# RUGGED RELIABLE MICRO SOCKETS

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?CLM](http://www.samtec.com?CLM) or [www.samtec.com?MLE](http://www.samtec.com?MLE)

### Insulator Material:

Black LCP

### Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

### Plating:

CLM: Au or Sn over 50 μ" (1.27 μm) Ni

MLE: Au over 10 μ" (0.25 μm) Ni

### Current Rating (CLM/FTM):

2.8 A per pin

(2 pins powered)

### Current Rating (MLE/FTM):

2.9 A per pin

(2 pins powered)

### Operating Temp Range:

-55 °C to +125 °C

### Max Cycles:

CLM: 100 with 10 μ" (0.25 μm) Au

### Voltage Rating:

MLE: 310 VAC

### Insertion Depth:

CLM: Top Entry = (1.40 mm)

.055" min., Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to

(3.18 mm) .125" with

(0.38 mm) .015" wiper,

pass-through, or

(2.44 mm) .096" minimum

for bottom entry

### Normal Force:

CLM: 40 grams (0.39 N) average

### RoHS Compliant:

Yes

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)\*

\*(.004" stencil solution

may be available; contact

IPG@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



CLM

1

NO. PINS PER ROW

02

PLATING OPTION

D

OPTIONS

Mates with:

FTM, FTMH, MW

02 thru 50

-F

= Gold flash on contact, Matte Tin on tail

-L

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-BE

= Bottom Entry (Required for bottom entry)

-K

= (3.50 mm) .138" DIA Polyimide film Pick &amp; Place Pad (7 positions minimum)

-P

= Pick &amp; Place Pad (7 positions minimum)

-PA

= Pick &amp; Place Pad with integral Alignment Pin

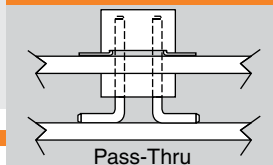
-TR

= Tape &amp; Reel Packaging

-FR

= Full Reel Tape &amp; Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

## APPLICATION



## ALSO AVAILABLE (MOQ Required)

- Alignment pin
- Other Gold plating options

MLE

1

NO. PINS PER ROW

01

PLATING OPTION

DV

OPTIONS

Mates with:

FTM, FTMH, MW

02 thru 50

-G

= 10 μ" (0.25 μm) Gold

-A

= Alignment Pin (3 positions minimum) Metal or plastic at Samtec discretion

-K

= (4.00 mm) .1575" DIA Polyimide film Pick &amp; Place Pad (5 positions minimum)

-P

= Metal Pick &amp; Place Pad (5 positions minimum)

-TR

= Tape &amp; Reel Packaging

**Note:**  
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.